



Material Content Data Sheet



Halogen-Free

Sales Product Name	IQE006NE2LM5CG	Issued	24. June 2021
MA#	MA005549212		
Package	PG-TTFN-9-1	Weight*	43.34 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.896	2.07	2.07	20687	20687
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		59	
	non noble metal	zinc	7440-66-6	0.010	0.02		237	
	non noble metal	iron	7439-89-6	0.205	0.47		4740	
	non noble metal	copper	7440-50-8	8.341	19.25	19.75	192472	197508
encapsulation	organic material	carbon black	1333-86-4	0.029	0.07		668	
	plastics	epoxy resin	-	1.491	3.44		34410	
	inorganic material	silicondioxide	60676-86-0	12.957	29.90	33.41	299002	334080
leadfinish	non noble metal	tin	7440-31-5	0.474	1.09	1.09	10946	10946
plating	noble metal	silver	7440-22-4	0.296	0.68	0.68	6837	6837
solder	noble metal	silver	7440-22-4	0.032	0.07		730	
	non noble metal	tin	7440-31-5	0.063	0.15		1460	
	non noble metal	lead	7439-92-1	1.171	2.70	2.92	27012	29202
heat sink clip	inorganic material	phosphorus	7723-14-0	0.004	0.01		102	
	non noble metal	iron	7439-89-6	0.015	0.03		340	
	non noble metal	copper	7440-50-8	14.697	33.92	33.96	339160	339602
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			17	
	non noble metal	iron	7439-89-6	0.002	0.01		56	
	non noble metal	copper	7440-50-8	2.416	5.58	5.59	55753	55826
clip attach	non noble metal	tin	7440-31-5	0.005	0.01		106	
	noble metal	silver	7440-22-4	0.006	0.01		133	
	non noble metal	lead	7439-92-1	0.220	0.51	0.53	5073	5312
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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